# **OSRAM** LB A673 **Datasheet**

Discontinued





#### **SIDELED®**

## **LB A673**





#### **Applications**

- Ambient Lighting

#### **Features**

- Package: white SMT package, colorless clear resin
- Chip technology: InGaN
- Typ. Radiation: 120° (Lambertian emitter)
- Color:  $\lambda_{dom}$  = 471 nm (• blue)
- Corrosion Robustness Class: 3B
- Qualifications: The product qualification test plan is based on the guidelines of AEC-Q101-REV-C, Stress Test Qualification for Automotive Grade Discrete Semiconductors.
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)



#### **Ordering Information**

Type Luminous Intensity  $^{1)}$  Ordering Code  $I_F = 10 \text{ mA}$ 

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LB A673-L2P1-35-1 14.0 ... 56.0 mcd Q65112A2758

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Maximum Ratings			
Parameter	Symbol		Values
Operating Temperature	$T_{op}$	min. max.	-40 °C 100 °C
Storage Temperature	$T_{stg}$	min. max.	-40 °C 100 °C
Junction Temperature	T <sub>j</sub>	max.	110 °C
Forward current T <sub>S</sub> = 25 °C	I <sub>F</sub>	max.	20 mA
Surge current t $\leq$ 10 $\mu$ s; D = 0.005 ; T <sub>s</sub> = 25 °C	I <sub>FS</sub>	max.	200 mA
Reverse voltage <sup>2)</sup> T <sub>S</sub> = 25 °C	$V_R$	max.	5 V
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)	$V_{ESD}$		2 kV

#### **Characteristics**

 $I_F$  = 10 mA;  $T_S$  = 25 °C

Parameter	Symbol		Values
Peak Wavelength	$oldsymbol{\lambda}_{peak}$	typ.	466 nm
Dominant Wavelength 3)	$\lambda_{\sf dom}$	min.	465 nm
I <sub>F</sub> = 10 mA		typ.	471 nm
		max.	477 nm
Spectral Bandwidth at 50% I <sub>rel,max</sub>	$\Delta \lambda$	typ.	25 nm
Viewing angle at 50% $\rm I_{_{\rm V}}$	2φ	typ.	120 °
Forward Voltage 4)	V <sub>F</sub>	min.	2.70 V
I <sub>F</sub> = 10 mA	·	typ.	3.10 V
		max.	3.40 V
Reverse current 2)	I <sub>R</sub>	typ.	0.01 μΑ
$V_R = 5 V$		max.	10 µA
Temperature Coefficient of Peak Wavelength -10°C ≤ T ≤ 100°C	$TC_{\lambda peak}$	typ.	0.04 nm / K
Temperature Coefficient of Dominant Wavelength -10°C ≤ T ≤ 100°C	$TC_{\lambda dom}$	typ.	0.03 nm / K
Real thermal resistance junction/ambient 5)6)	$R_{thJA\ real}$	max.	430 K / W
Real thermal resistance junction/solderpoint 5)	$R_{thJSreal}$	max.	200 K / W



#### **Brightness Groups**

Group	Luminous Intensity 1)	Luminous Intensity. 1)	Luminous Flux 7)
	$I_F = 10 \text{ mA}$	$I_F = 10 \text{ mA}$	$I_F = 10 \text{ mA}$
	min.	max.	typ.
	l <sub>v</sub>	l <sub>v</sub>	$\Phi_{v}$
L2	14.0 mcd	18.0 mcd	48.0 mlm
M1	18.0 mcd	22.4 mcd	60.6 mlm
M2	22.4 mcd	28.0 mcd	75.6 mlm
N1	28.0 mcd	35.5 mcd	95.3 mlm
N2	35.5 mcd	45.0 mcd	120.8 mlm
P1	45.0 mcd	56.0 mcd	151.5 mlm

#### **Forward Voltage Groups**

Group	Forward Voltage <sup>4)</sup> I <sub>F</sub> = 10 mA min. V <sub>F</sub>	Forward Voltage <sup>4)</sup> I <sub>F</sub> = 10 mA max. V <sub>F</sub>	
Z4	2.70 V	2.90 V	
46	2.90 V	3.20 V	
A4	3.20 V	3.40 V	

### Wavelength Groups

Group	Dominant Wavelength 3)	Dominant Wavelength 3)
	$I_F = 10 \text{ mA}$	$I_F = 10 \text{ mA}$
	min.	max.
	$\lambda_{\sf dom}$	$\lambda_{dom}$
3	465 nm	469 nm
4	469 nm	473 nm
5	473 nm	477 nm



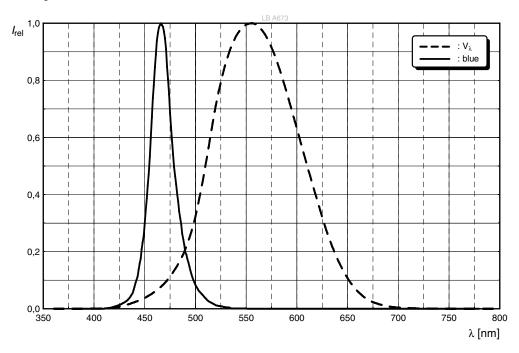
#### **Group Name on Label**

Example: L2-3-46

L2 3 46

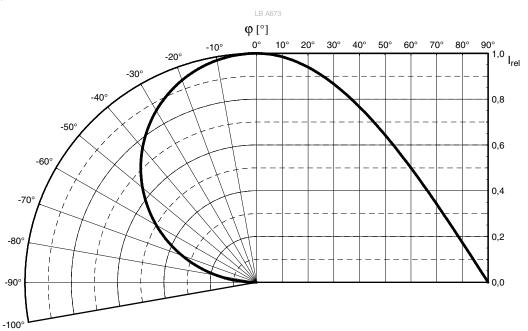
#### Relative Spectral Emission 7)

 $I_{rel}$  = f ( $\lambda$ );  $I_{F}$  = 10 mA;  $T_{S}$  = 25 °C



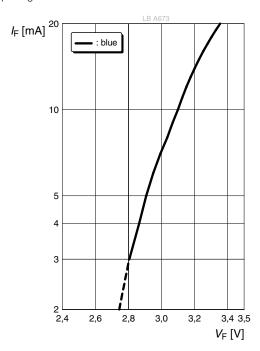
#### Radiation Characteristics 7)

 $I_{rel} = f(\phi); T_S = 25 °C$ 



#### Forward current 7), 8)

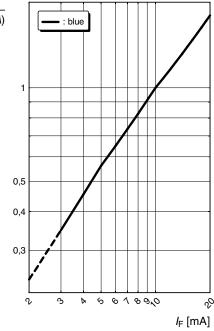
$$I_F = f(V_F); T_S = 25 \, ^{\circ}C$$



#### Relative Luminous Intensity 7), 8)

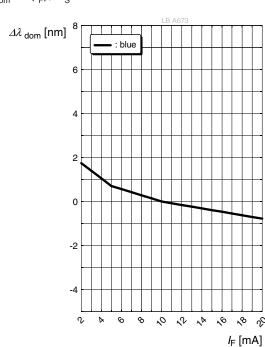
$$I_{v}/I_{v}(10 \text{ mA}) = f(I_{F}); T_{S} = 25 \text{ °C}$$





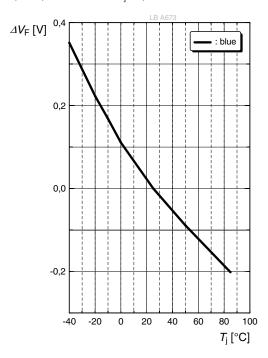
#### Dominant Wavelength 7)

$$\Delta\lambda_{dom} = f(I_F); T_S = 25 \text{ }^{\circ}\text{C}$$



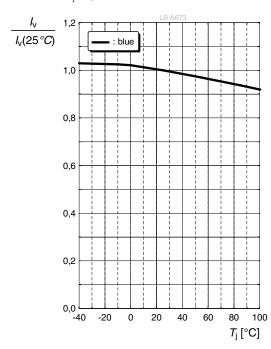
#### Forward Voltage 7)

$$\Delta V_{_F} = V_{_F} - V_{_F} (25~^{\circ}C) = f(T_{_j}); \ I_{_F} = 10~mA$$



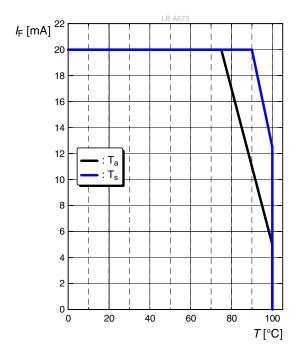
#### Relative Luminous Intensity 7)

$$I_{v}/I_{v}(25 \text{ °C}) = f(T_{j}); I_{F} = 10 \text{ mA}$$



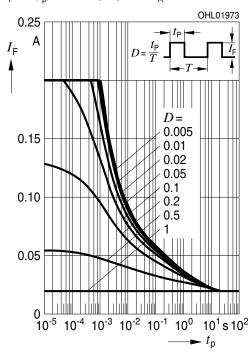
#### Max. Permissible Forward Current

 $I_F = f(T)$ 



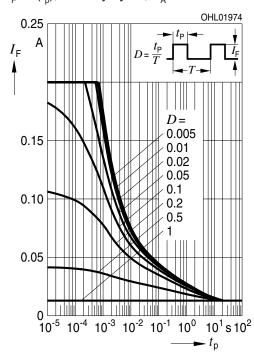
#### Permissible Pulse Handling Capability

 $I_F = f(t_p)$ ; D: Duty cycle;  $T_A = 25 \, ^{\circ}C$ 



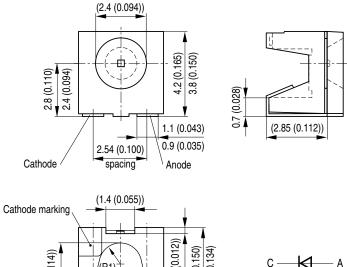
#### Permissible Pulse Handling Capability

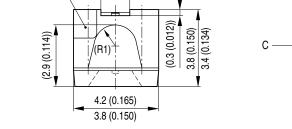
 $I_{_{\rm F}}$  = f(t $_{_{
m D}}$ ); D: Duty cycle;  $T_{_{
m A}}$  = 85 °C





#### **Dimensional Drawing** 9)





#### **Further Information:**

**Approximate Weight:** 67.0 mg

Corrosion test: Class: 3B

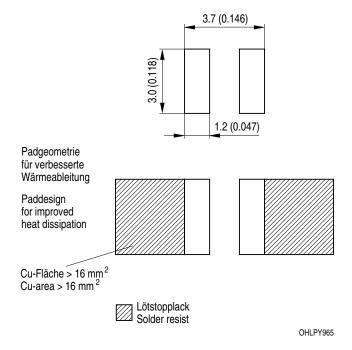
Test condition: 40°C / 90 % RH / 15 ppm H<sub>2</sub>S / 14 days (stricter than IEC

GPLY6880

60068-2-43)



#### Recommended Solder Pad 9)

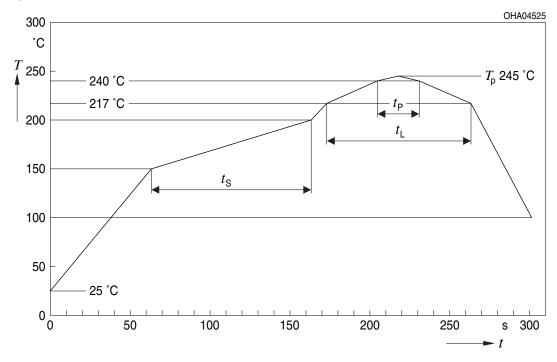


For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for ultra sonic cleaning.



#### **Reflow Soldering Profile**

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E

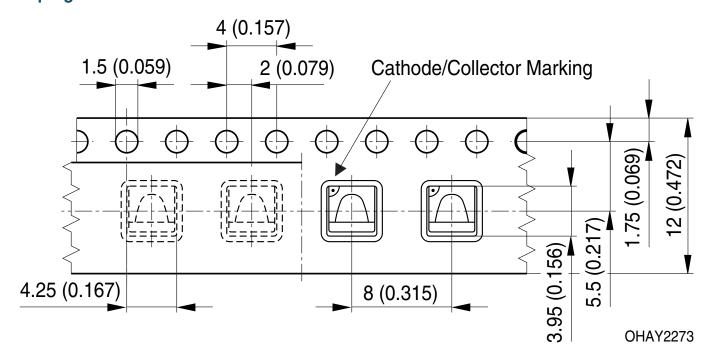


Profile Feature	Symbol	Symbol Pb-Free (SnAgCu) Assembly			Unit	
		Minimum	Recommendation	Maximum		
Ramp-up rate to preheat*)			2	3	K/s	
25 °C to 150 °C						
Time t <sub>s</sub>	$t_s$	60	100	120	S	
$T_{Smin}$ to $T_{Smax}$						
Ramp-up rate to peak*)			2	3	K/s	
$T_{Smax}$ to $T_{P}$						
Liquidus temperature	$T_L$		217		°C	
Time above liquidus temperature	$t_{\scriptscriptstyle \perp}$		80	100	S	
Peak temperature	T <sub>P</sub>		245	250	°C	
Time within 5 °C of the specified peak temperature T <sub>p</sub> - 5 K	t <sub>P</sub>	10	20	30	S	
Ramp-down rate* T <sub>P</sub> to 100 °C			3	4	K/s	
Time 25 °C to T <sub>P</sub>				480	S	

All temperatures refer to the center of the package, measured on the top of the component

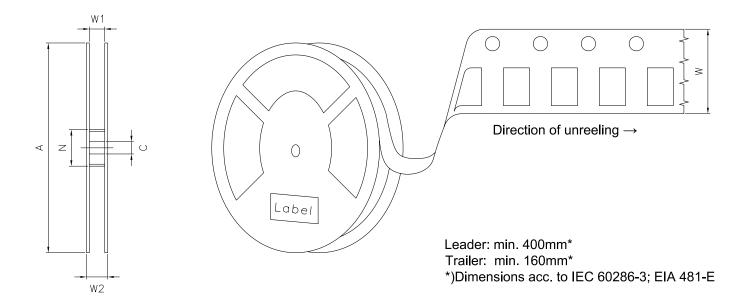
<sup>\*</sup> slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range

#### Taping 9)





#### Tape and Reel 10)

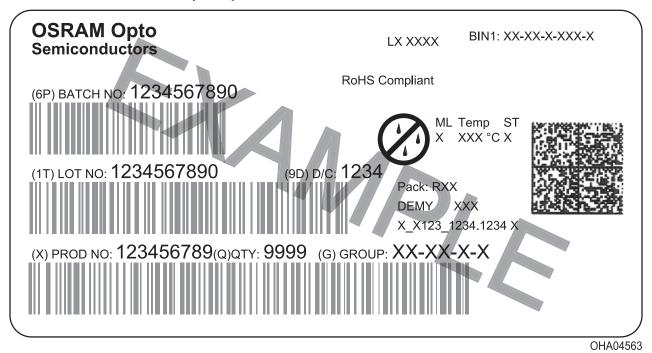


#### **Reel Dimensions**

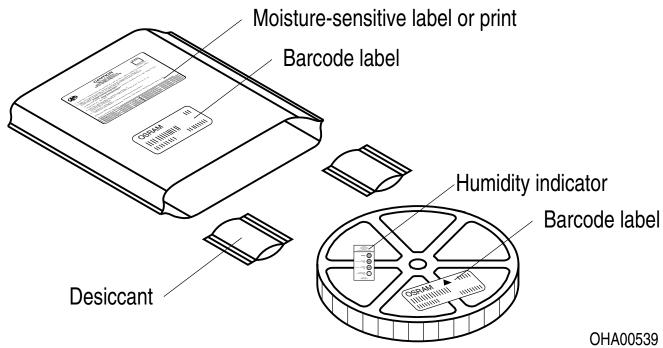
Α	W	$N_{\min}$	$W_1$	$W_{2\text{max}}$	Pieces per PU
330 mm	12 + 0.3 / - 0.1 mm	60 mm	12.4 + 2 mm	18.4 mm	2000



#### **Barcode-Product-Label (BPL)**



#### Dry Packing Process and Materials 9)



Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.

#### **Notes**

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet fall into the class **exempt group (exposure time 10000 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related information please visit www.osram-os.com/appnotes

#### Disclaimer

#### Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on our website.

#### **Packing**

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

#### Product and functional safety devices/applications or medical devices/applications

Our components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

Our products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using our components in product safety devices/ applications or medical devices/applications, buyer and/or customer has to inform our local sales partner immediately and we and buyer and /or customer will analyze and coordinate the customer-specific request between us and buyer and/or customer.

#### Glossary

- Brightness: Brightness values are measured during a current pulse of typically 25 ms, with an internal reproducibility of ±8 % and an expanded uncertainty of ±11 % (acc. to GUM with a coverage factor of k = 3).
- 2) Reverse Operation: This product is intended to be operated applying a forward current within the specified range. Applying any continuous reverse bias or forward bias below the voltage range of light emission shall be avoided because it may cause migration which can change the electro-optical characteristics or damage the LED.
- Wavelength: The wavelength is measured at a current pulse of typically 25 ms, with an internal reproducibility of ±0.5 nm and an expanded uncertainty of ±1 nm (acc. to GUM with a coverage factor of k =
- 4) Forward Voltage: The forward voltage is measured during a current pulse of typically 8 ms, with an internal reproducibility of ±0.05 V and an expanded uncertainty of ±0.1 V (acc. to GUM with a coverage factor of k = 3).
- 5) **Thermal Resistance:** Rth max is based on statistic values  $(6\sigma)$ .
- 6) Thermal Resistance: RthJA results from mounting on PC board FR 4 (pad size 16 mm² per pad)
- 7) Typical Values: Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- 8) Characteristic curve: In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.
- 9) Tolerance of Measure: Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.
- Tape and Reel: All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.

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Revision History				
Version	Date	Change		
1.4	2020-09-21	Features Schematic Transportation Box Dimensions of Transportation Box		
1.5	2022-04-21	New Layout Not for new design		
1.6	2022-08-03	Discontinued Applications		

#### Discontinued



EU RoHS and China RoHS compliant product 此产品符合欧盟 RoHS 指令的要求; 按照中国的相关法规和标准, 不含有毒有害物质或元素。

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